



QUALITEK®

365F Flux Low Solids, No-Clean

DESCRIPTION

365F no-clean is a homogeneous mixture of halogen-free, low solids flux designed for wave soldering conventional and surface mount PCB assemblies. 365F provides excellent activity and yields very low post soldering residue. The unique solvent system used in 365F allows for a very broad process window by remaining active after the chip wave.

BENEFITS

- Halide Free
- Remains active after the chip wave
- Low residue
- Bright, shiny solder joints
- Pin testable
- Virtually eliminates solder balls and bridging

APPLICATION METHODS

365F no-clean flux may be applied by foam, spray, or wave methods. Flux deposition, density, and uniformity are critical to successful use of low solids no-clean flux. After foam or wave application, an air knife should be used to remove excess flux from the assembly. Pre-heating the assembly will partially volatilize the solvents, enhance oxide removal, and promote optimum wicking and solder joint formation. The optimum pre-heat temperature range is 100^o-120^oC (210^o-250^oF) on the top side of the assembly.

PACKAGING & STORAGE

365F flux is available in 1, 5 and 55 gallon containers. It should be stored in cool, dry place away from ignition sources.

PHYSICAL & CHEMICAL CHARACTERISTICS

Color and Appearance	Colorless Liquid
Solids Content, % (By Wt.)	2.0 – 2.5
Specific Gravity	0.850 +/- 0.006
Flash Point	53°F
Acid Number	16.0 – 20.0
Flux Classification per J-STD-004	ORL0
Copper Mirror Test	Pass (No complete removal)
Silver Chromate Test	
Chloride and Bromide	Pass (No discoloration)
Spot Test (Flouride)	Pass (No color change)
Corrosion Test	Pass (No evidence of corrosion)
Shelf life (un-opened)	2 years

PROCESS CONTROL

Control of the flux is necessary to ensure a consistent amount of flux is applied to assemblies. Due to the very low solids percentage of no-clean fluxes, specific gravity is not an accurate measure for solids content. Monitoring and controlling acid number is recommended to maintain the proper flux concentration. Titration may be accomplished with the Qualitek HDT-200 Digital Titration Kit. Control of the flux can be achieved with Qualitek 300A thinner. Debris and contaminants will accumulate in the flux reservoir. Periodically, the replacement of the flux is required for consistent soldering performance, and to prevent debris build-up on the circuit assemblies. This should be performed every 35-40 hours of operation.

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Consult MSDS for health and safety information